

Title (en)

Chip board panel, method and apparatus of manufacturing the panel

Title (de)

OSB-Platte sowie Verfahren und Vorrichtung zu ihrer Herstellung

Title (fr)

Plaque composite en bois, procédé et appareil pour la fabrication de la plaque

Publication

EP 1721715 A1 20061115 (DE)

Application

EP 06007021 A 20060401

Priority

DE 102005021903 A 20050512

Abstract (en)

The method involves arranging wood chips or wood fibers glued with resin in several layers (6, 7, 8) to form a splinter or fiber cake and pressing the wood chips or wood fibers together by applying pressure and temperature. At least one layer material insert (4, 5), in particular a fleece, a fabric, plastic or paper insert, is introduced between the layers before pressing and is pressed with the wood fibers or wood chips. Independent claims are also included for the following: (A) a wood material board (B) and a device for manufacturing a wood material board .

IPC 8 full level

B27N 3/06 (2006.01)

CPC (source: EP)

B27N 3/06 (2013.01); **B27N 3/14** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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Designated extension state (EPC)

AL BA HR MK YU

DOCDB simple family (publication)

EP 1721715 A1 20061115; EP 1721715 B1 20100818; AT E477897 T1 20100915; DE 102005021903 A1 20061116; DE 102005021903 B4 20080710; DE 502006007671 D1 20100930; ES 2349871 T3 20110112; PL 1721715 T3 20110228

DOCDB simple family (application)

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